Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Currently amended) A mold comprising:
a support comprising a composite material of a thermoplastic polyolefin polymeric material and 20 to 70 percent volume based on the composite of a glass fiber reinforcing material blended with the polymeric material, and
a shape-imparting surface layer disposed on the support; wherein the mold has a coefficient of hydroscopic swelling of less than 5 ppm per percent relative humidity.

2. (original) The mold of claim 1 wherein the mold is flexible.

3. (original) The mold of claim 1 wherein the shape-imparting surface layer is microstructured.

4. (original) The mold of claim 3, wherein the microstructured surface comprises a groove pattern.

5. (original) The mold of claim 3, wherein the microstructured surface comprises a protrusion pattern.

6-8. (cancelled)

9. (Currently Amended) The mold of claim [[~~8~~]] 1 wherein said polyolefin is a polypropylene or a cycloolefin.

10. (Currently Amended) The mold of claim 1, wherein said ~~composite~~ thermoplastic polyolefin polymeric material comprises polypropylene ~~and glass fiber~~.

11. (original) The mold of claim 1, wherein said shape-imparting layer comprises a cured resin composition.

12. (original) The mold of claim 11, wherein said cured resin composition is photocured.

13. (original) The mold of claim 3, wherein the microstructured surface is a protrusion pattern corresponding to barrier ribs for a back plate of a plasma display panel.

14-16. (cancelled)

17. (Previously presented) The mold of claim 1, wherein the coefficient of hydroscopic swelling is less than 3 ppm per percent relative humidity.

18. (Previously presented) The mold of claim 1, wherein the coefficient of hydroscopic swelling is less than 1 ppm per percent relative humidity.

19. (original) A method of making a microstructured article comprising

providing the mold of claim 1;

disposing a curable material between a substrate and the shape-imparting microstructured surface layer of the mold;

curing the curable material; and

removing the mold.

20-23. (Canceled)